



# Product Change Notification

**Change Notification #:** 117573 - 00  
**Change Title:** Intel® Server System R1208WT2GSR,  
Intel® Server System R1208WTTGSR,  
Intel® Server System R1304WT2GSR,  
Intel® Server System R1304WTTGSR,  
PCN 117573-00, Product Design,  
ESD gaskets addition on PCI Riser Bracket  
**Date of Publication:** April 24, 2020

## Key Characteristics of the Change:

Product Design

## Forecasted Key Milestones:

<b>Date Customer Must be Ready to Receive Post-Conversion Material: *</b>	May 9, 2020
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\*Intel appreciates the customer's desire to receive the latest revision of products. However, Intel manages inventory on a first in first out (FIFO) basis at the MM# level. Subsequently, customer requests for a specific revision of material (below the MM#) will not be supported by Intel.

## Description of Change to the Customer:

Intel is adding two adhesive ESD gaskets on the top and behind of the PCI riser bracket included in the Intel® Server Systems listed in the "Products Affected" table below. The ESD gaskets are added to prevent ESD issues that could be caused by voltage discharge.

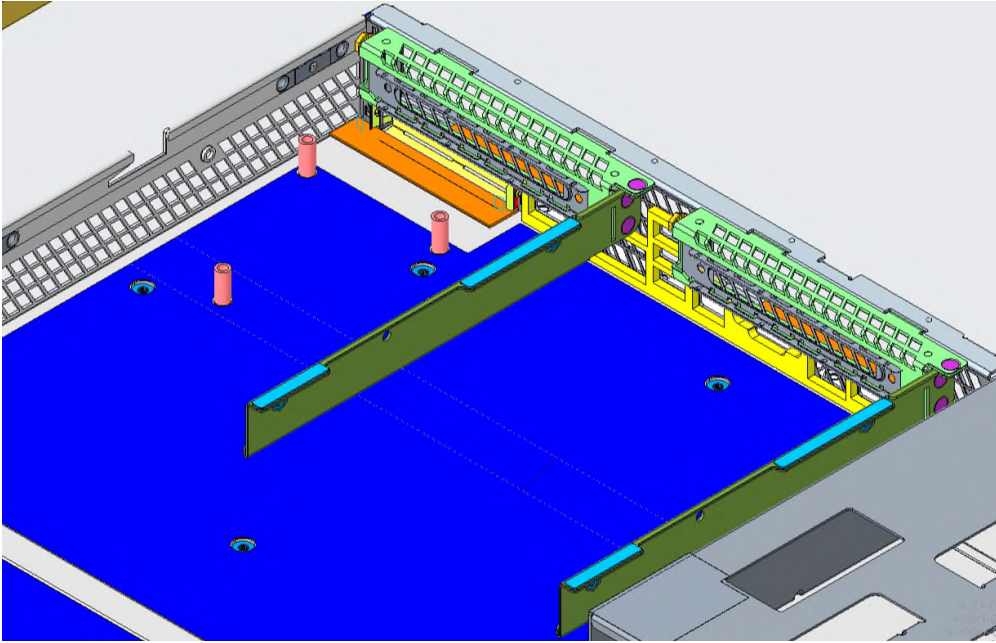


Image 1. Riser bracket before ESD gasket added

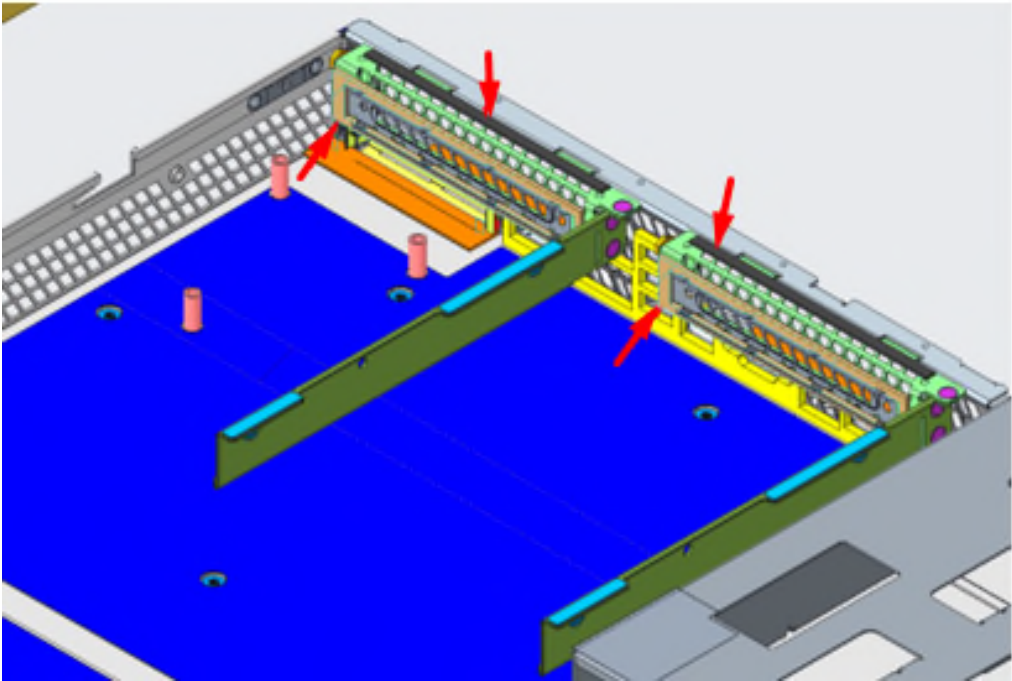


Image 2. Riser bracket after ESD gasket added

## Customer Impact of Change and Recommended Action:

Intel does not expect any other impact to customers from this change, but encourages customers to understand the change and determine the impact on their applications.

Please contact your local Intel Field Sales Rep if you have any further questions about these changes.

## Products Affected / Intel Ordering Codes:

Product Code	MM#	Pre Change TA	Post Change TA
R1208WT2GSR	975756	J11465-016	J11465-017
R1208WTTGSR	977047	J11481-019	J11481-020
R1304WT2GSR	977053	J11483-017	J11483-018
R1304WTTGSR	977052	J11482-013	J11482-014

## PCN Revision History:

**Date of Revision:**

April 24, 2020

**Revision Number:**

00

**Reason:**

Originally Published PCN



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**Should you have any issues with the timeline or content of this change, please contact the Intel Representative(s) for your geographic location listed below. No response from customers will be deemed as acceptance of the change and the change will be implemented pursuant to the key milestones set forth in this attached PCN.**

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